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Substrate Sawing Process for a Strip-

Abstract of the Disclosure

The substrate sawing process for a strip mainly includes multi-alignment corresponding to a plurality of substrate areas of strips which are arranged side-by-side on a plate. A saw machine is mechanically moved to the substrate areas and is positioned by the alignments of corresponding substrate areas for cutting the substrate areas of the strips in the first phase. Then the saw machine is further mechanically moved to the substrate areas again and is positioned by the alignments of corresponding substrate areas again for cutting the substrate areas of the strips in the second phase. Therefore, an error in any of the substrate areas in the first phase and second phase cannot add to the peripheral substrate areas.